Future Trends in SoC Interconnect

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Abstract— Self-timed packet-switched networks are poised to take a major role in addressing the problems of timing closure power management and overwhelming complexity in the design of Systems-on-Chip. The robust, correct-byconstruction characteristics of self-timed communications enables each IP block on the SoC to operate in its own isolated timing domain, greatly simplifying the problems of timing validation. The inherent data-driven nature of the self-timed network, combined with the improved wire segmentation provided by the switched network architecture gives greatly improved power management. Design automation software can remove the need for expertise in self-timed design and networking principles, enabling the on-chip interconnect to be treated as an additional IP block within a conventional (synchronous) design flow. The paradigm shift from viewing the SoC design problem as a matter of organizing complex hierarchies of buses with multiple coupled timing domains, where every interface between timing domains must be verified carefully, to viewing the SoC as a problem in network design where those timing issues are automatically isolated, promises significant improvements in designer productivity, component reuse and SoC functionality.

I. INTRODUCTION

The System-on-Chip (SoC) industry has developed rapidly over the last fifteen years from producing VLSI devices that integrated a processor and a few memory and peripheral components onto a single chip to today's high-performance SoCs that incorporate hundreds of IP blocks. This progress is a consequence of Moore's Law (which enables ever-higher levels of integration) and of market economics (where consumers demand ever-more functionality in smaller, lower-cost products with better battery life).

Complex systems have always been hard to build and debug. Systems-on-chip are no different in this respect, but the economics of integrated circuit manufacture do not allow debugging by trial and error; the design must be 'right first time'. As a result, SoC designers adopt disciplines that minimize the risk of design error. One such discipline is to

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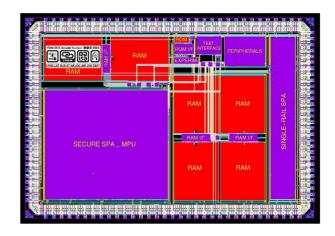


Figure 1. The smart card chip incorporating the prototype CHAIN self-timed Network-on-Chip.

be very systematic about the way interconnect is used on a complex chip. Any communication failure, whether due to noise or an error in timing or protocol, is likely to require a design iteration that will be expensive in both mask charges and time to market.

II. SoC interconnect evolution

The Early SoCs used an interconnect paradigm inspired by the rack-based microprocessor systems of earlier days where, a backplane of parallel connections formed a 'bus' into which all manner of cards could be plugged. A system designer could select cards from a catalogue and simply plug them into the rack to yield a customized system with the processor, memory and interfaces required for any given application.

In a similar way, a designer of an early SoC could select IP blocks, place them onto the silicon, and connect them together with a standard on-chip bus. The backplane might not be apparent as a set of parallel wires on the chip, but logically the solution is the same.

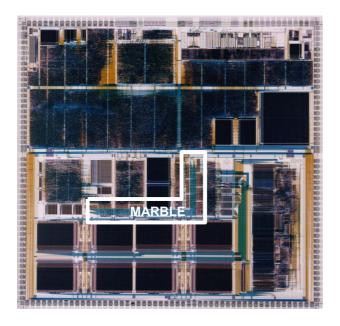


Figure 2. Draco chip plot showing the asynchronous MARBLE bus.

However, buses do not scale well. With the rapid rise in the number of blocks to be connected and the increase in performance demands, today's SoCs cannot be built around a single bus. Instead, complex hierarchies of buses are used, with sophisticated protocols and multiple bridges between them. Partitioning the system in this manner permits concurrent communications on different buses, and reduces the power consumption by lowering the switched load involved in each communication. In such systems, communication between two remote blocks can go via several buses, and every section of every path must be carefully verified. Timing closure is a growing problem because there is so much that must be checked. Bus-based interconnect is being stretched to its limit, and as the limit is approached the risk of errors increases rapidly. A new interconnect strategy is required to bring these risks back under control.

An example of a complex system-on-chip that employs the hierarchical bus solution is the Draco DECT-ISDN controller chip (Fig. 2) which was based around the Amulet3i asynchronous processing subsystem [1]. This chip incorporates two local processor buses serving the instruction and data requirements of the Harvard architecture Amulet3 processor core, the asynchronous multi-master MARBLE bus with production test support [2], and a bridge to a synchronous on-chip bus that serves the clocked telecommunication peripherals.

III. NETWORKS-ON-CHIP

Where bus-based solutions reach their limit, packetswitched networks are poised to take over [3]. A packet switched network offers flexibility in topology (see Fig. 3) and trade-offs in the allocation of resources to clients.

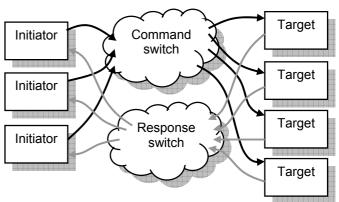


Figure 3. A packet-switched Network-on-Chip offers the most flexible interconnect structure.

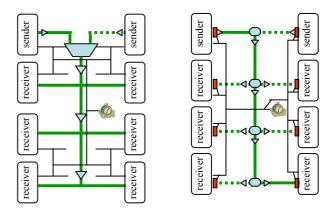


Figure 4. Architectural effect of bus (left) and NoC (right) on switched wire load and clock distribution requirements.

Furthermore, it brings architectural improvements that can allow greater concurrency, and the distribution of switches and pipeline stages throughout the network greatly reduces the wire-load switched for a given communication. This is illustrated in Fig. 4 which shows (in solid lines) the wire switched for a communication from the top-left sender to the bottom-right receiver, and also shows the simpler clock distribution requirements of the self-timed NoC versus the synchronous bus.

Such a network has been developed at the University of Manchester [4] and demonstrated on a prototype smart card chip [5]. The layout of the smart card chip is shown in Fig. 1, and the CHAIN interconnect can be seen as the top-level wiring and the small logic blocks associated with it.

This Network-on-Chip (NoC) employs self-timed logic techniques to deliver a robust, correct-by-construction interconnection fabric that allows each client block to operate in its own fully-decoupled timing domain, thereby addressing system-level timing-closure issues and allowing optimal choice of the clock frequency for each IP block, further reducing system power consumption.

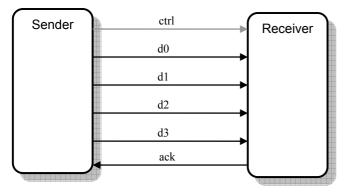


Figure 5. A CHAIN point-to-point self-timed link.

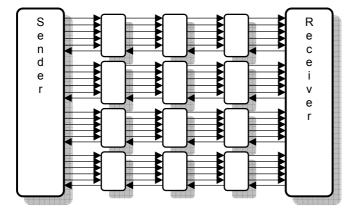


Figure 6. A wide, long CHAIN connection with parallel links and pipeline repeaters.

The principles of the CHAIN self-timed point-to-point interconnect are illustrated in Fig. 5. The link employs a 1-of-4 data encoding to send 2 bits of data by switching one of the 4 data wires using a return-to-zero protocol.

Every transition is acknowledged, thereby ensuring that variations in transmission delay (due, for example, to crosstalk) are accommodated automatically. A 5th data wire is used to indicate control activity such as the end-of packet, resulting in a 6-wire data link. This link has been demonstrated operating at a 500 MHz symbol rate (where each symbol is 2 bits of data) on a 0.18 micron CMOS process, yielding a data throughput of 1 Gbit per 6-wire link.

Where a single link provides insufficient performance, multiple links can be deployed in parallel and individual links can be pipelined, as shown in Fig. 6. An example of a pipeline repeater circuit is shown in Fig. 7. Five Muller C gates form the latches, holding the 1-of-4 data and the control bit. The 5-input NOR gate is a 'completion detection' circuit, indicating when one of the latches has been set. The repeater forms one stage of a Muller pipeline and can be used to divide long point-to-point links into shorter sections, thereby counteracting the throughput problems created by the delays inherent in driving long wires. The self-timed nature of CHAIN means that the exact number of pipeline

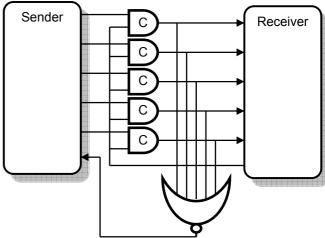


Figure 7. A CHAIN pipeline repeater.

latches used in an end-to-end path is not as critical as for synchronous buses or NoCs – in CHAIN overly liberal use of latches adds slightly to the latency, similarly to overbuffering the signals whereas even one too many latches in an equivalent synchronous NoC or bus connection adds significantly (whole clock cycles) to the end-to-end latency. Of course, long wires still introduce end-to-end latency problems, but these are inherent in any on-chip communication system.

The switching technology in CHAIN comprises 2-to-1 multiplexers and 1-to-2 demultiplexers. With these components a range of standard network topologies can be implemented, such as a basic mux-demux topology, crossbar mesh structures, and even an on-chip ring. Although technically feasible, rings do not seem well-suited to on-chip interconnect as their efficiency depends on multiple packets being in transit simultaneously within the ring fabric, which does not occur with the latencies that arise on chip.

IV. NETWORK CONFIGURATION

Configuring an NoC to support the functionality and performance requirements of a complex SoC is still a daunting task. However, this is a task that can be addressed by design automation software. Silistix Limited, a company spun-out from the University of Manchester and formed around the NoC team, is developing sophisticated tools that will enable the interconnect fabric to be treated as just another synthesizable IP block integrated into the standard design flow (Fig. 8). This will eliminate the risks inherent in current bus-based interconnect methodologies and bring timing-closure problems down to manageable size.

Once the full SoC interconnect requirements have been specified, the Silistix CHAINworks tool will generate the appropriate network structure, selecting link widths, pipeline repeaters and switching topology to meet those requirements at minimum cost. The tools fit into a conventional SoC design flow as shown in Fig. 9, removing any need for the

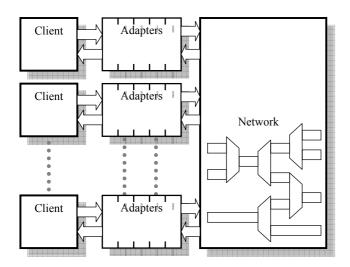


Figure 8. The Silistix Self-Timed Network-on-Chip design approach.

designer to have any knowledge or expertise in self-timed design.

V. FUTURE REQUIREMENTS

The Silistix tools will provide designer-friendly support for self-timed networks-on-chip that will deliver a robust and cost-effective solution to the requirement for a systematic approach to on-chip interconnect for complex systems-on-chip. Beyond this, the future presents many design challenges for on-chip interconnect.

Quality-of-Service (QoS) support is an obvious next-step, and the feasibility of providing QoS support on an asynchronous NoC has already been demonstrated [6]. At present the cost of implementing QoS is high compared with a best-effort network such as CHAIN, where it is always possible to provide dedicated links for specific connections that require guaranteed performance.

The current CHAIN technology assumes that on-chip logic is reliable. It is tolerant to delay variations, but it is not designed to recover from logic faults or failures. It may become necessary to design on the basis that on-chip logic is fallible, so that fault-tolerance becomes a requirement for all on-chip functions, including interconnect. Interconnect could be made fault-tolerant by building redundancy into the fabric, but it is likely to be more cost-effective (at the low expected error rates) to implement error detection and retry capabilities into the interfaces, effectively adding fault-tolerance as a layer on top of an unreliable fabric (as is the case with off-chip networks).

As system complexity increases and the interconnect provides new features such as QoS, fault recovery and reconfigurability to support platform-based design methods, new techniques will be required for on-chip real-time monitoring and analysis of the network's ability to satisfy demands. The interconnect will not only have to self-monitor

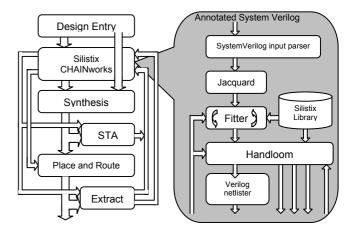


Figure 9. The Silistix Self-Timed Network-on-Chip design flow.

and adjust to system demands, but will also have to provide extended hardware support for software debug of systems built around the NoC.

VI. CONCLUSIONS

Packet-switched networks-on-chip are the clear solution to the problem of complex SoC interconnect, and future developments will see advances in these networks to improve their performance, flexibility, power-efficiency and functionality. Self-timed NoCs offer further advantages in terms of power-efficiency and timing closure. Design automation tools, such as those from Silistix Limited, will enable the integration of self-timed NoCs into tomorrow's complex SoCs without disrupting established design flows.

Support for Quality-of-Service protocols, fault-tolerance, secure communication and other similar high-level functions will emerge over the next few years to establish the NoC as the de-facto on-chip interconnect technology.

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